



**IHS NORMALIZED FORMAT
Material Declaration Data Sheet**

Added
Normalized

Document Code	ANDIE00002
Material Table Identifier	QSOP 150 MILS - 20 (Pb FREE)

Sub Part	Sub Part Weight (mg)	Sub Part Details	Sub Part Substance	CAS Number	Sub Part Substance Weight (mg)	Sub Part Substance Concentration (ppm)
MOLD COMPOUND	60.939		EPOXY RESIN	NOT PROVIDED	6.09	99936
MOLD COMPOUND	60.939		SILICA,VITREOUS	60676-86-0	51.8	850030
MOLD COMPOUND	60.939		PHENOL RESIN	NOT PROVIDED	1.83	30030
MOLD COMPOUND	60.939		ANTIMONY OXIDE	1309-64-4	0.914	14999
MOLD COMPOUND	60.939		BROMINATED RESIN	NOT PROVIDED	0.305	5005
LEAD FRAME	50.3556		COPPER	7440-50-8	49.1	975065
LEAD FRAME	50.3556		IRON	7439-89-6	1.18	23433
LEAD FRAME	50.3556		PHOSPHORUS	7723-14-0	0.0151	300
LEAD FRAME	50.3556		ZINC	7440-66-6	0.0605	1201
INTERNAL LEAD FRAME PLATING	0.556		SILVER	7440-22-4	0.556	1000000
EXTERNAL LEAD FRAME PLATING	2.69		TIN	7440-31-5	2.69	1000000
BOND WIRE	0.525		GOLD	7440-57-5	0.525	1000000
CHIP	4.85		SILICON	7440-21-3	4.85	1000000
DIE ATTACH	0.3134		RESIN	NOT PROVIDED	0.0784	250160
DIE ATTACH	0.3134		SILVER FILLER	NOT PROVIDED	0.235	749840
Total Weight (mg)					120.229	